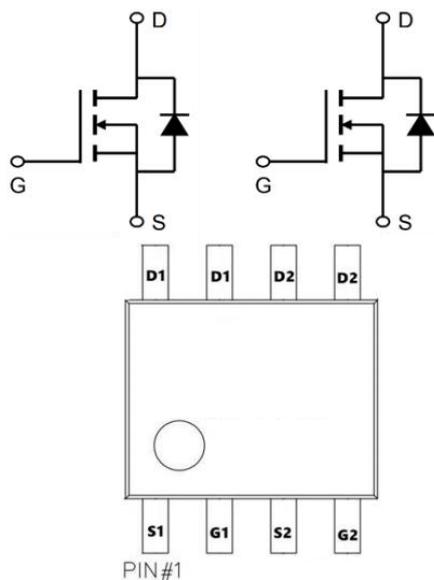


### Description

The SX8H06S uses advanced trench technology to provide excellent  $R_{DS(ON)}$ , low gate charge and operation with gate voltages as low as 4.5V. This device is suitable for use as a Battery protection or in other Switching application.



### General Features

$V_{DS} = 60V$   $I_D = 8A$

$R_{DS(ON)} < 32m\Omega$  @  $V_{GS}=10V$

### Application

- Battery protection
- Load switch
- Uninterruptible power supply

### SOP-8



### Absolute Maximum Ratings ( $T_c=25^\circ C$ unless otherwise noted)

Symbol	Parameter	Rating	Units
VDS	Drain-Source Voltage	60	V
VGS	Gate-Source Voltage	$\pm 20$	V
$I_D@T_A=25^\circ C$	Continuous Drain Current, $V_{GS}$ @ 10V <sup>1</sup>	8.2	A
$I_D@T_A=70^\circ C$	Continuous Drain Current, $V_{GS}$ @ 10V <sup>1</sup>	5.8	A
IDM	Pulsed Drain Current <sup>2</sup>	16.6	A
EAS	Single Pulse Avalanche Energy <sup>3</sup>	28.5	mJ
IAS	Avalanche Current	22.6	A
$P_D@T_A=25^\circ C$	Total Power Dissipation <sup>4</sup>	1.5	W
TSTG	Storage Temperature Range	-55 to 150	$^\circ C$
TJ	Operating Junction Temperature Range	-55 to 150	$^\circ C$
R $\theta$ JA	Thermal Resistance Junction-Ambient <sup>1</sup>	85	$^\circ C/W$
R $\theta$ JC	Thermal Resistance Junction-Case <sup>1</sup>	36	$^\circ C/W$

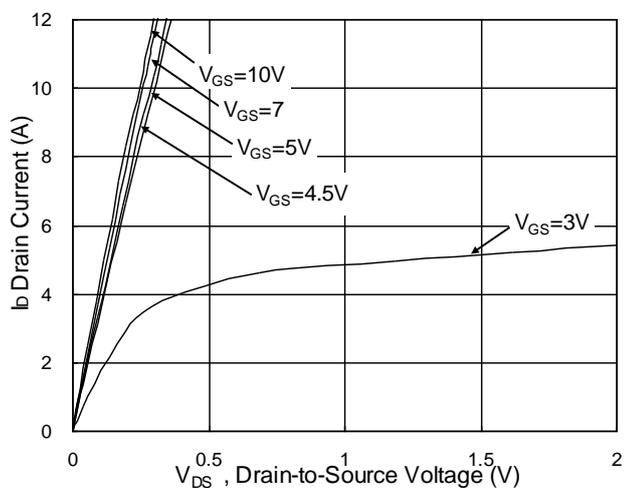
**Electrical Characteristics ( $T_J=25^{\circ}\text{C}$ , unless otherwise noted)**

Symbol	Parameter	Conditions	Min	Typ.	Max	Unit
BVDSS	Drain-Source Breakdown Voltage	$V_{GS}=0V, I_D=250\mu A$	60	66	---	V
$\Delta BVDSS/\Delta T_J$	BV <sub>DSS</sub> Temperature Coefficient	Reference to $25^{\circ}\text{C}$ , $I_D=1\text{mA}$	---	0.063	---	V/ $^{\circ}\text{C}$
RDS(ON)	Static Drain-Source On-Resistance <sup>2</sup>	$V_{GS}=10V, I_D=8A$	---	23	32	m $\Omega$
		$V_{GS}=4.5V, I_D=6A$	---	28	38	
VGS(th)	Gate Threshold Voltage	$V_{GS}=V_{DS}, I_D=250\mu A$	1.2	1.6	2.5	V
$\Delta V_{GS(th)}$	V <sub>GS(th)</sub> Temperature Coefficient		---	-5.24	---	mV/ $^{\circ}\text{C}$
IDSS	Drain-Source Leakage Current	$V_{DS}=48V, V_{GS}=0V, T_J=25^{\circ}\text{C}$	---	---	1	$\mu\text{A}$
		$V_{DS}=48V, V_{GS}=0V, T_J=55^{\circ}\text{C}$	---	---	5	
IGSS	Gate-Source Leakage Current	$V_{GS}=\pm 20V, V_{DS}=0V$	---	---	$\pm 100$	nA
gfs	Forward Transconductance	$V_{DS}=5V, I_D=4A$	---	21	---	S
R <sub>g</sub>	Gate Resistance	$V_{DS}=0V, V_{GS}=0V, f=1\text{MHz}$	---	3.2	6.4	$\Omega$
Q <sub>g</sub>	Total Gate Charge (4.5V)	$V_{DS}=48V, V_{GS}=4.5V, I_D=4A$	---	12.6	---	nC
Q <sub>gs</sub>	Gate-Source Charge		---	3.2	---	
Q <sub>gd</sub>	Gate-Drain Charge		---	6.3	---	
T <sub>d(on)</sub>	Turn-On Delay Time	$V_{DD}=30V, V_{GS}=10V, R_G=3.3\Omega, I_D=4A$	---	8	---	ns
T <sub>r</sub>	Rise Time		---	14.2	---	
T <sub>d(off)</sub>	Turn-Off Delay Time		---	24.4	---	
T <sub>f</sub>	Fall Time		---	4.6	---	
C <sub>iss</sub>	Input Capacitance	$V_{DS}=15V, V_{GS}=0V, f=1\text{MHz}$	---	1378	---	pF
C <sub>oss</sub>	Output Capacitance		---	86	---	
C <sub>rss</sub>	Reverse Transfer Capacitance		---	64	---	
I <sub>S</sub>	Continuous Source Current <sup>1,5</sup>	$V_G=V_D=0V, \text{Force Current}$	---	---	4.8	A
I <sub>SM</sub>	Pulsed Source Current <sup>2,5</sup>		---	---	9.6	A
VSD	Diode Forward Voltage <sup>2</sup>	$V_{GS}=0V, I_S=1A, T_J=25^{\circ}\text{C}$	---	0.746	1.2	V

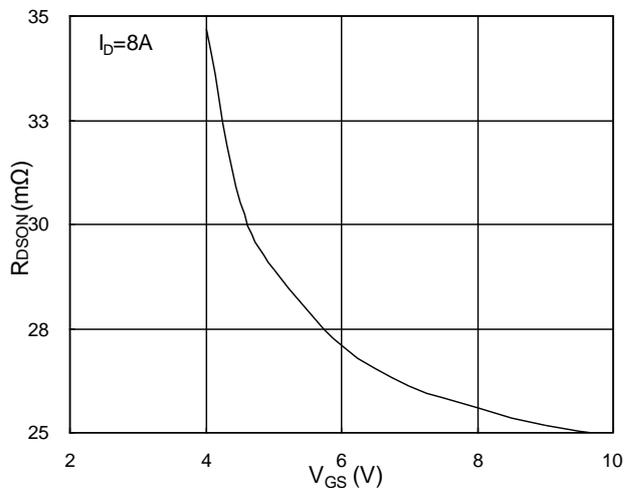
Note :

- 1.The data tested by surface mounted on a 1 inch<sup>2</sup> FR-4 board with 2OZ copper.
- 2.The data tested by pulsed , pulse width  $\leq 300\mu\text{s}$  , duty cycle  $\leq 2\%$
- 3.The EAS data shows Max. rating . The test condition is  $V_{DD}=25V, V_{GS}=10V, L=0.1\text{mH}, I_{AS}=22.6A$
- 4.The power dissipation is limited by  $150^{\circ}\text{C}$  junction temperature
- 5.The data is theoretically the same as  $I_D$  and  $I_{DM}$  , in real applications , should be limited by total power dissipation.

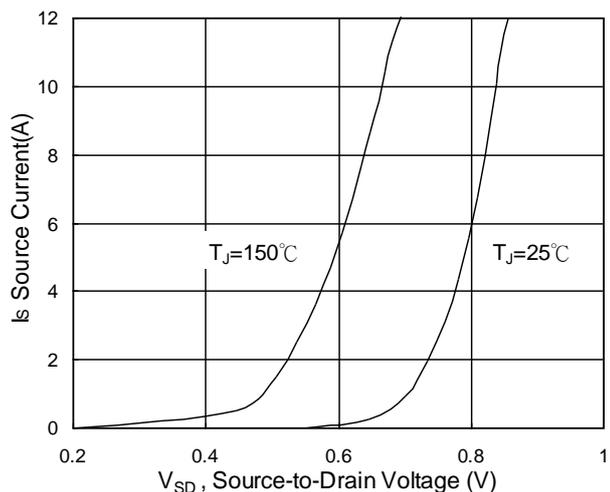
**Typical Characteristics**



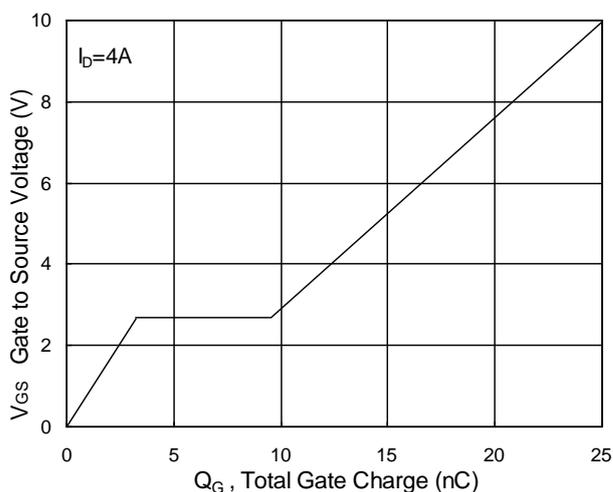
**Fig.1 Typical Output Characteristics**



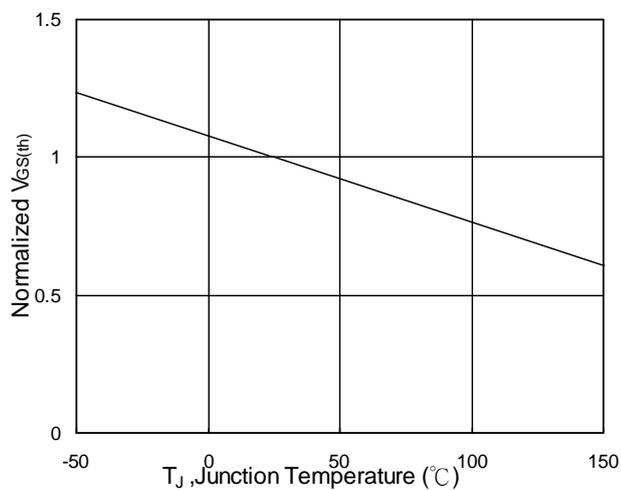
**Fig.2 On-Resistance v.s Gate-Source**



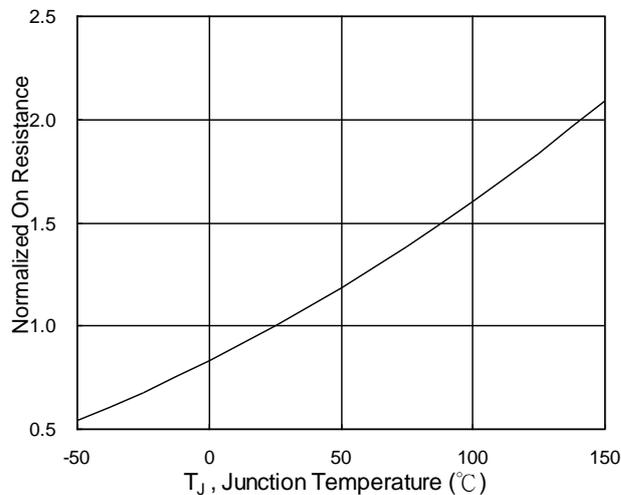
**Fig.3 Forward Characteristics of Reverse**



**Fig.4 Gate-Charge Characteristics**



**Fig.5 Normalized  $V_{GS(th)}$  v.s  $T_J$**



**Fig.6 Normalized  $R_{DS(on)}$  v.s  $T_J$**

Typical Characteristics

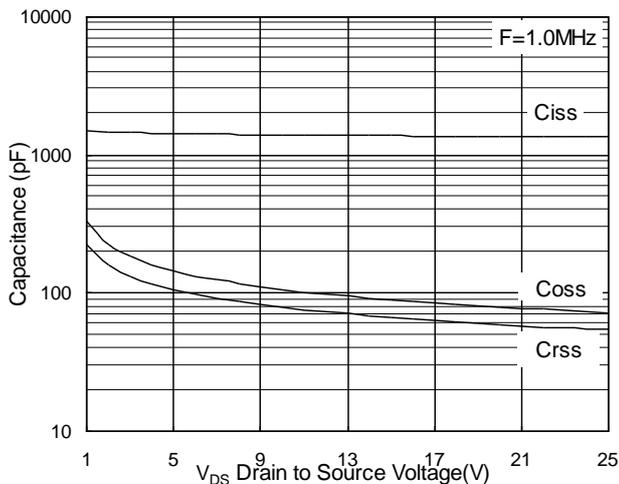


Fig.7 Capacitance

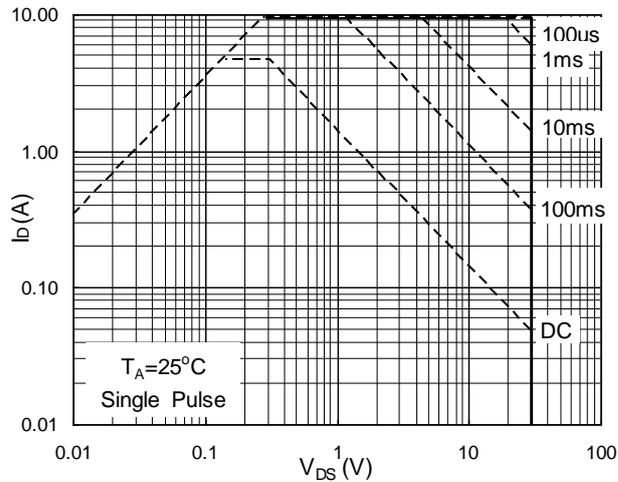


Fig.8 Safe Operating Area

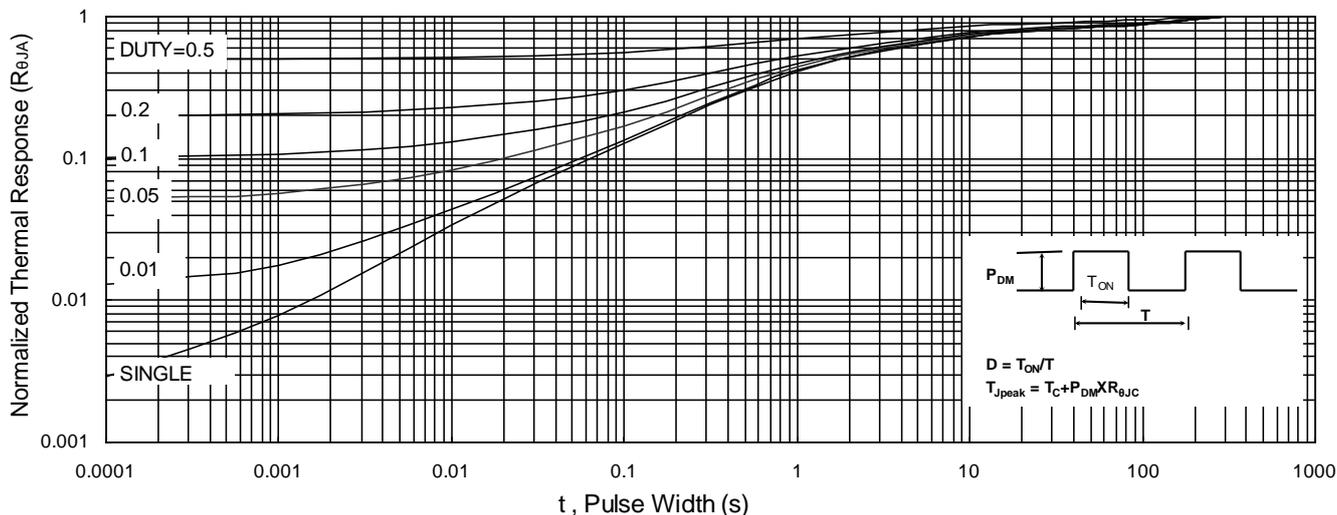


Fig.9 Normalized Maximum Transient Thermal Impedance

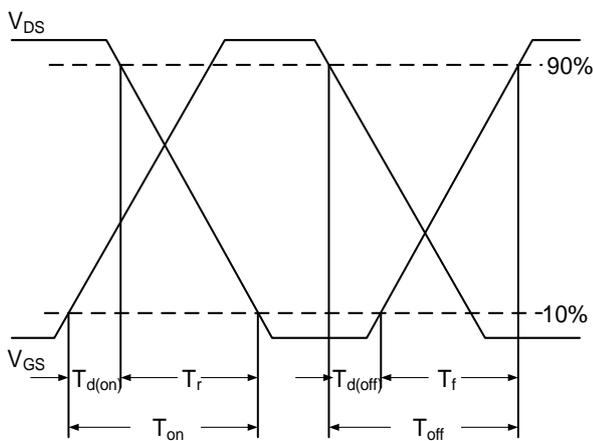


Fig.10 Switching Time Waveform

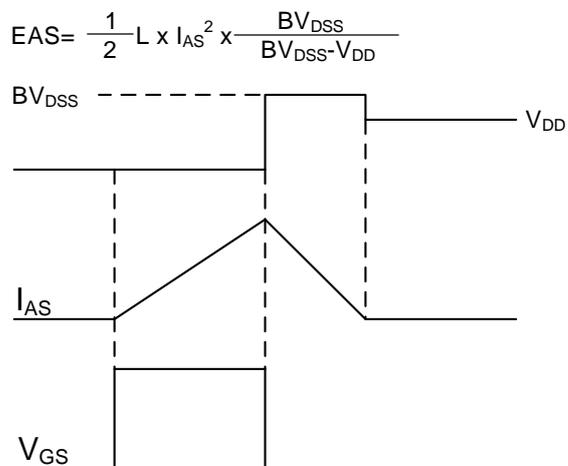
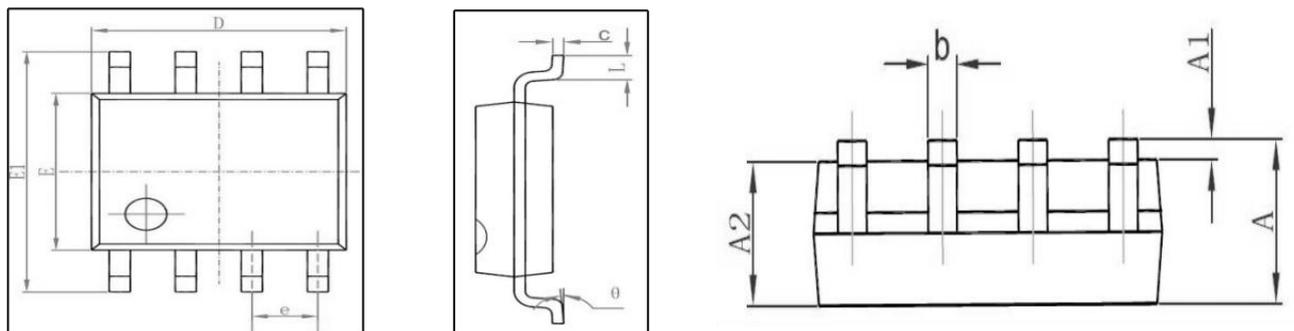
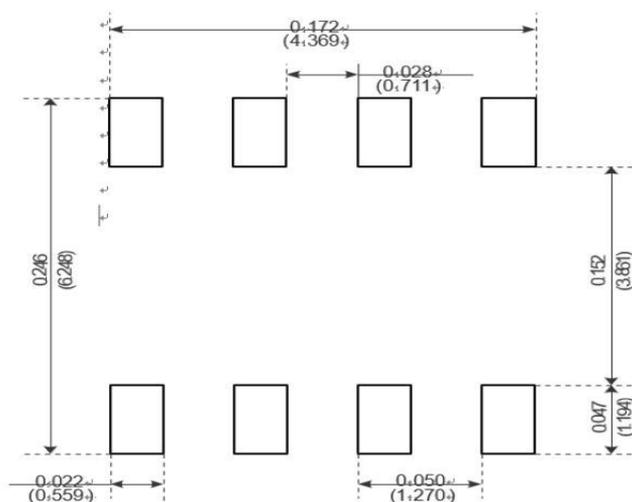


Fig.11 Unclamped Inductive Waveform

**Package Mechanical Data-SOP-8**



Symbol	Dimensions In Millimeters		Dimensions In Inches	
	Min	Max	Min	Max
A	1.350	1.750	0.053	0.069
A1	0.100	0.250	0.004	0.010
A2	1.350	1.550	0.053	0.061
b	0.330	0.510	0.013	0.020
c	0.170	0.250	0.006	0.010
D	4.700	5.100	0.185	0.200
E	3.800	4.000	0.150	0.157
E1	5.800	6.200	0.228	0.244
e	1.270 (BSC)		0.050 (BSC)	
L	0.400	1.270	0.016	0.050
θ	0°	8°	0°	8°



Recommended Minimum Pads

**Package Marking and Ordering Information**

Product ID	Pack	Marking	Qty(PCS)
TAPING	SOP-8		3000